# ZETTLER DISPLASYS

# SPECIFICATIONS FOR LIQUID CRYSTAL DISPLAY

	CUSTOMER APP	ROVAL	
W DADENG	1 0 1 5 0 0 0 0 1 W W G D W	VALUE DE DIG	DIANG HEDAA
* PART NO.:	AQM0802A-FLW-GBW		PLAYS) VER1.1
APPROVAL		COMPANY CHOP	
CUSTOMER			
COMMENTS			

ZETTLER DI	ZETTLER DISPLAYS ENGINEERING APPROVAL											
DESIGN BY	CHECKED BY APPROVED BY											
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## **REVISION RECORD**

	RECORD	DACE	CONTENTS
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## 1.0 GENERAL SPECS

1. Display Format	8*2 Character
2. Power Supply	3.3V
3. Overall Module Size	30.0mm(W) x 19.5mm(H) x max 5.5mm(D)
4. Viewing Aera(W*H)	27.0mm(W) x 10.5mm(H)
5. Dot Size (W*H)	0.45mm(W) x 0.50mm(H)
6. Dot Pitch (W*H)	0.50mm(W) x 0.55mm(H)
7. Character Size (W*H)	2.45mm(W) x 4.35mm(H)
8. Character Pitch (W*H)	2.95mm(W) x 4.90mm(H)
9. Viewing Direction	6:00 O'Clock
10. Driving Method	1/16Duty,1/5Bias
11. Controller IC	ST7032I OR EQUIV
12. Display mode	STN (GRAY) /Positive/ Transflective
13. Backlight Options	LED-SIDE(White)
14. Operating temperature	-20°C ~ 70°C
15. Storage temperature	-30°C ~ 80°C
16. RoHS	RoHS Compliant

## 2.0 ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Min	Тур	Max	Unit
Operating temperature	Тор	-20	-	70	°C
Storage temperature	Tst	-30	-	80	°C
Input voltage	Vin	Vss		Vdd	V
Supply voltage for logic	Vdd- Vss	2.7	-	5.5	V
Supply voltage for LCD drive	Vdd- Vo	3.0	-	7.0	V

## 3.0 ELECTRICAL CHARACTERISTICS

#### 3.1 Electrical Characteristics Of LCM

Item	Symbol	Condition	Min	Тур	Max	Unit
Power Supply Voltage	Vdd	25°C		3.3		V
Power Supply Current	ldd	Vdd=5.0V, fosc=270kHz				mA
Input voltage (high)	Vih	H level	0.8Vdd		Vdd	V
Input voltage (low)	Vil	L level	0		0.2Vdd	V
		-20°C				
Recommended LC Driving		25°C	4.3	4.5	4.7	V
Voltage	Vdd -Vo	70°C				

### 3.2 The Characteristics Of LED Backlight

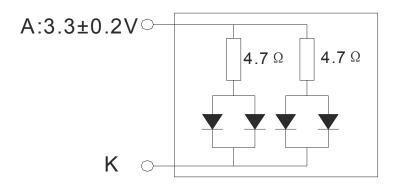
## 3.2.1 Electrical-Optical Characteristics Of LED Backlight (Ta=25°C)

Item	Symbol	Condition	Min	Тур	Max	Unit
Forward Voltage <sup>(1)</sup>	Vf	If=60mA	3.1	3.3	3.5	V
Reverse Voltage	Vr	-			4	V
Luminance <sup>(2)</sup>	Lv	If=60mA	100			cd/m²
Uniformity <sup>(3)</sup>	Δ	(Lvmin/Lvmax)%	70%			-
Peak wave length	λр					nm
Chroma coordinate	x	If=60mA	0.26		0.30	um
Chroma coordinate	у	If=60mA	0.27		0.31	um
Lifetime <sup>(4)</sup>	-	If=60mA	-	20000	-	Hours

#### NOTE:

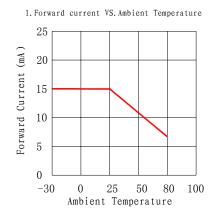
- (1) Forward voltage means voltage applied directly to the LED
- (2) The luminance is the average value of 5 points, The measurement instrument is BM-7 luminance colorimeter. The diameter of aperture is  $\Phi$ 5mm
  - (3) Luminance means the backlight brightness without LCD.
  - (4) Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

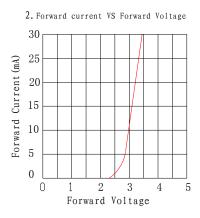
### 3.2.2 Backlight Control Circuit For LCM (1x4=4 pcs LED)



## 3.2.3 LED Typical Electro-Optical Characteristics Curve (for single led)

- 1. Forward current vs. Ambient temperature
- 2. Forward current vs. Forward voltage

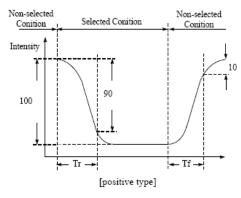


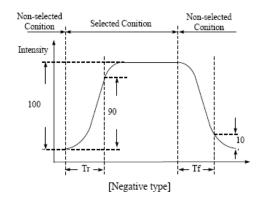


## 4.0 OPTICAL CHARACTERISTICS (Ta=25°C, Vdd= 3.3V±0.25V)

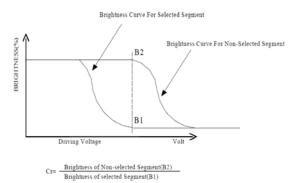
Item	Symbol	Condition	Min	Тур	Max	Unit
Viewing angle (horizontal)	θ	Cr ≥ 2.0	-35	-	35	deg
Viewing angle (vertical)	φ		-25	-	40	deg
Contrast Ratio	Cr	φ=0°, θ=0°	-	3	-	
Response time (rise)	Tr	φ=0°, θ=0°	-	180	300	ms
Response time (fall)	Tf	φ=0°, θ=0°	-	150	250	ms

## (1). Definition of Optical Response Time

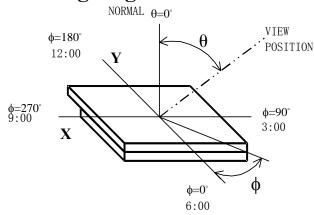




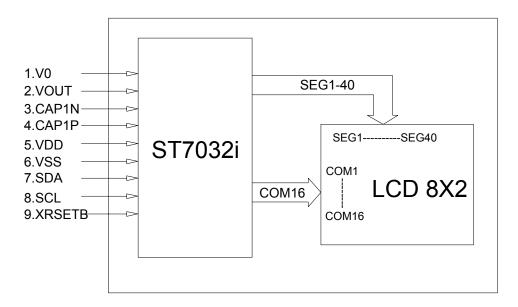
# (2). Definition of Contrast Ratio



# (3). Definition of Viewing Angle $\theta$ and $\Phi$



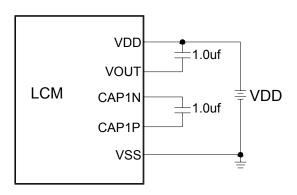
#### **5.0 BLOCK DIAGRAM**



## **6.0 PIN ASSIGNMENT**

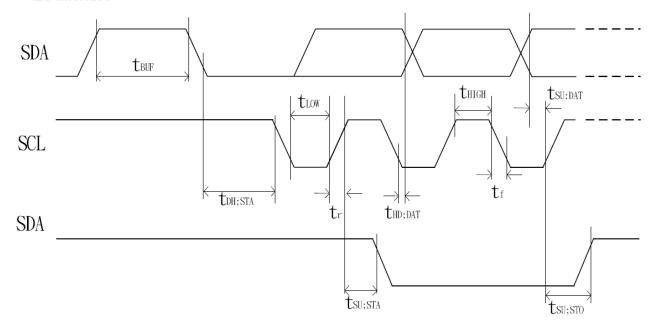
Pin No.	Symbol	Function
1	VO	Test PIN for VLCD,leave it open
2	VOUT	DC/DC voltage converter output
3	CAPIN	For voltage booster circuit(VDD-VSS)
4	CAPIP	External capacitor about 0.1u~4.7uf
5	VDD	+3.3V
6	VSS	Ground
7	SDA	Serial data input
8	SCL	Serial clock input
9	XRSETB	Chip reset signal. Active when low

## 7.0 POWER SUPPLY



## **8.0 TIMING CHARACTERISTICS**

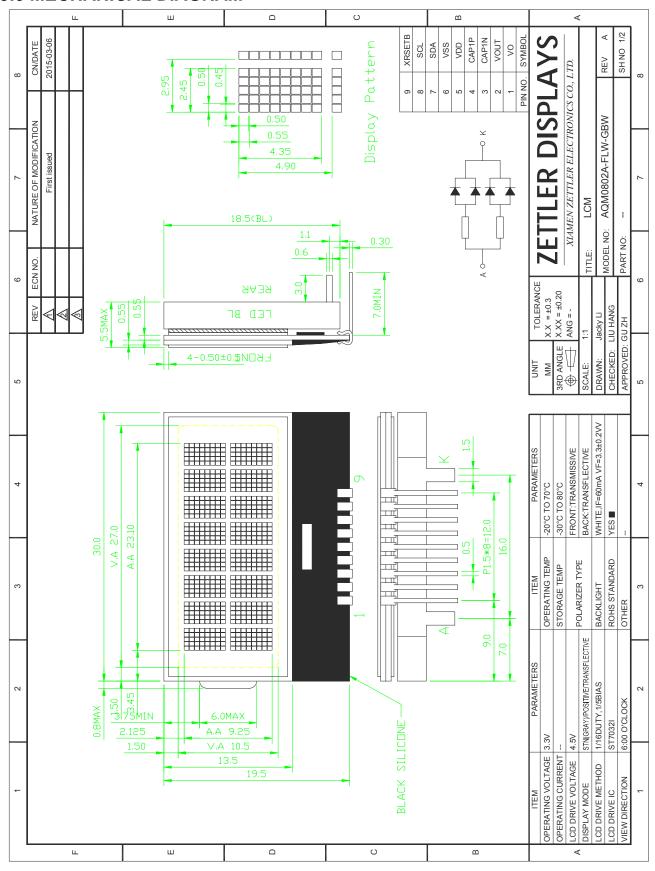
#### I2C interface

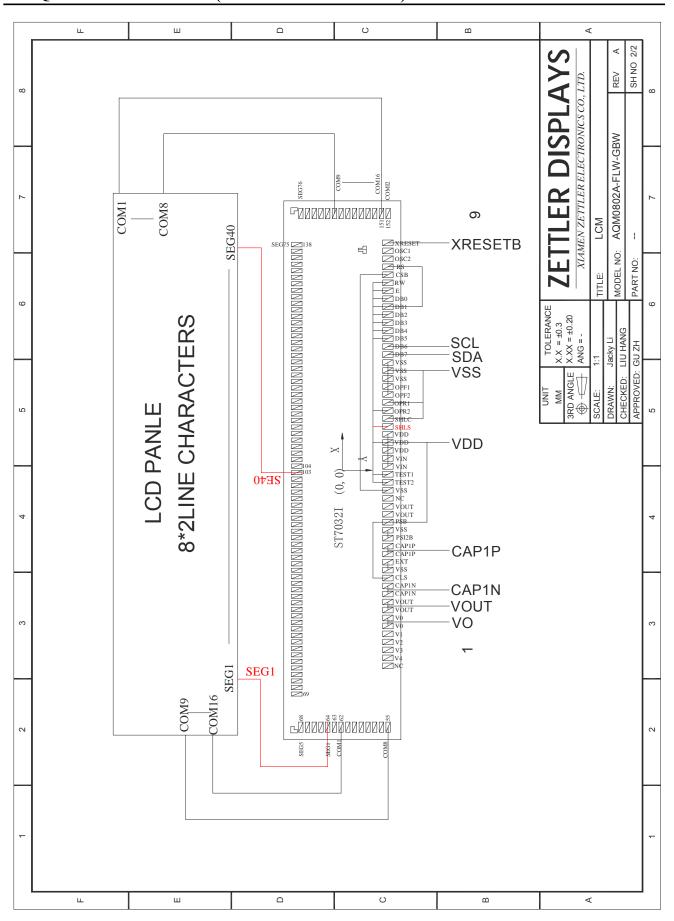


( Ta =-30°C to 85°C )

Item	Signal	Symbol	Condition	VDD=2.7 Rati		VDD=4.5 Rati	Units	
item	Signal	Symbol	Condition	Min.	Max.	Min.	Max.	Onits
SCL clock frequency		f <sub>SCLK</sub>		DC	400	DC	400	KHz
SCL clock low period	SCL	<b>t</b> LOW	_	1.3		1.3	_	110
SCL clock high period		t <sub>HIGH</sub>		0.6	_	0.6	_	us
Data set-up time	SI	$t_{\text{SU;DAT}}$		180	_	100	_	ns
Data hold time	SI	t <sub>HD:DAT</sub>		0	0.9	0	0.9	us
SCL,SDA rise time	SCL,	$\mathbf{t}_{r}$		20+0.1Cb	300	20+0.1Cb	300	ns
SCL,SDA fall time	SDA	t <sub>f</sub>	_	20+0.1C₀	300	20+0.1C <sub>0</sub>	300	115
Capacitive load represent by each bus		C <sub>b</sub>	_	_	400	_	400	pf
Setup time for a repeated START condition	SI	t <sub>SU;STA</sub>	_	0.6	_	0.6	_	us
Start condition hold time		t <sub>HD;STA</sub>	_	0.6	_	0.6	_	us
Setup time for STOP condition		t <sub>SU;STO</sub>	_	0.6	_	0.6	_	us
Bus free time between a Stop and START condition	SCL	t <sub>BUF</sub>	_	1.3	_	1.3	_	us

## 9.0 MECHANICAL DIAGRAM





## **10.0 RELIABILITY TEST**

NO	П	Test Item	Description	<b>Test Condition</b>	Remark
1		High temperature storage	Applying the high storage temperature Under normal humidity for a long time Check normal performance	80 <b>°</b> C 96hrs	
2		Low temperature storage	Applying the low storage temperature Under normal humidity for a long time Check normal performance	-30 <b>°</b> C 96hrs	
3		High temperature Operation	Apply the electric stress(Volatge and current) Under high temperature for a long time	70 <b>°</b> C 96hrs	Note1
4	Environmenta	Low temperature Operation	Apply the electric stress Under low temperature for a long time	-20 <b>º</b> C 96hrs	Note1 Note2
5	Test	High temperature/High Humidity Storage	Apply high temperature and high humidity storage for a long time	90% RH 40 <b>°</b> C 96hrs	Note2
6		Temperature Cycle	Apply the low and high temperature cycle -30°C <> 25°C <> 80°C <> 25°C 30min 10min 30min 10min  1 cycle Check normal performance	-30 <b>º</b> C/80 <b>º</b> C 10 cycle	
7	Mechanical Test	Vibration test(Package state)	Applying vibration to product check normal performance	Freq:10-55Hz Max Acceleration 5G 1cycle time:1min time X.Y.Z direction for 15 mines	
8		Shock test(package state)	Applying shock to product check normal performance	Drop them through 70cm height to strike horizontal plane	
9	Other			<u>F</u> <u>I</u>	

#### Remark

Note1:Normal operations condition (25°C±5°C).

Note2:Pay attention to keep dewdrops from the module during this test.

## 11.0 DISPLAY INSTRUCTION Table

#### > instruction table at "Extension mode"

(when "EXT" option pin connect to Vss, the instruction set follow below table)

In atmostice	•	Instruction Code									December (able)	Instruction Execution Time			
Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description		OSC= 540kHz	OSC= 700KHz	
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC	1.08 ms	0.76 ms	0.59 ms	
Return Home	0	0	0	0	0	0	0	0	1	х	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.08 ms	0.76 ms	0.59 ms	
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	s	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	26.3 us	18.5 us	14.3 us	
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1:entire display on C=1:cursor on B=1:cursor position on	26.3 us	18.5 us	14.3 us	
Function Set	0	0	0	0	1	DL	N	DH	*0	IS	DL: interface data is 8/4 bits N: number of line is 2/1 DH: double height font IS: instruction table select	26.3 us	18.5 us	14.3 us	
Set DDRAM address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	26.3 us	18.5 us	14.3 us	
Read Busy flag and address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0	0	0	
Write data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM/ICONRAM)	26.3 us	18.5 us	14.3 us	
Read data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM/ICONRAM)	26.3 us	18.5 us	14.3 us	

Note \*: this bit is for test command , and must always set to "0"

	Instruction table 0(IS=0)													
											S/C and R/L:			
Cursor or Display Shift	ift 0	0 0	_	_	_	1	0/0	R/L	١.,		Set cursor moving and display shift	26.2 116	19.5.00	112 110
			U	U	0	U	'	S/C	R/L	х	X	Set cursor moving and display shift control bit, and the direction, without	20.5 us	10.5 us
											changing DDRAM data.			
Set CGRAM	•	_	•		۸05		400	400	۸.04		Set CGRAM address in address	26.2.110	18.5 us	11 2 110
Set CGRAIN	0	0 0	0 0	1	ACS	AC4	ACS	AC2	AC1	ACO	counter	20.5 us	10.5 US	14.3 US

Instruction table 1(IS=1)														
Internal OSC frequency	0	0	0	0	0	1	BS	F2	F1	F0	BS=1:1/4 bias BS=0:1/5 bias F2~0: adjust internal OSC frequency for FR frequency.	26.3 us	18.5 us	14.3 us
Set ICON address	0	0	0	1	0	0	AC3	AC2	AC1	AC0	Set ICON address in address counter.	26.3 us	18.5 us	14.3 us
Power/ICON control/Contrast set		0	0	1	0	1	Ion	Bon	C5	C4	lon: ICON display on/off Bon: set booster circuit on/off C5,C4: Contrast set for internal follower mode.	26.3 us	18.5 us	14.3 us
Follower control	0	0	0	1	1	0	Fon	Rab 2	Rab 1	Rab 0	Fon: set follower circuit on/off Rab2~0: select follower amplified ratio.	26.3 us	18.5 us	14.3 us
Contrast set	0	0	0	1	1	1	СЗ	C2	C1	C0	Contrast set for internal follower mode.	26.3 us	18.5 us	14.3 us

## 12.0 STANDARD CHARACTER PATTERNS

# ST7032-0D (ITO option OPR1=1, OPR2=1)

					_,					Τ,						
67-64 63-60	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
0000																
0001																
0010																
0011																
0100																
0101																
0110																
0111																
1000																
1001																
1010																
1011																
1100																
1101																
1110																
1111																

## 13.0 APPEARANCE CRITERIA

Item	Description	Picture	Specification				MA	MI	Inspection Method
Dot defects (black/wh	Scratches		≤0.1 Ignored						Visual/
	black dot white dot on	Ь	0.1< ∮≤0.20		2	J>5			contrast by
ite dot)	the polarizer dirty spot	$\phi = \frac{a+b}{2}$	0.20< $\phi$ ≤0.25		1	J>10			Inspection standard
	and bubble between the polarizer and	J:the distance	0.25< ∮ ≤0.30		0				film
	glass in the display area.	between dot and dot.	0φ>0.3		0				
black/white	Fibres in	, ₩	W≤0.01		Ignored				Visual/
line defect (straight	active area, scratches	***	W≤0.02 L≤5		2	J>5			contrast by
line or	and black line on the		W≤0.03 L≤4		1	J>10			Inspection standard
curve etc. Line type	glass or	L	W≤0.04 L≤3		0	J>10			film
defects)	polarizer.	J:the distance between dot and dot.	W≤0.05 L≤2		0				
Chip on corner	sidestep on the lower	T.	Y≤1/2L, X≤1		Ignored				Visual/ contrast
	glass	Youidth of ohio	Y≤1/2L, X≤2		2				by Inspection
			Y≤1/2L, X≤3		1				standard film
		Y:width of chip X:length of chip L:width of sidestep	Y≤1/2L, X≤1/3.	J	0	J≤3	=		
		J:distance between electrode and the farthermost edge.	Y≤1/2L, X≤2/3	J	0	J≤3			
Crack			Y≤1/5L X≤5 ≤1/2T	Z	Ignored				Visual/ contrast
			Y≤1/4L X≤5 Z ≤1/2T		2				by Inspection standard
		Y:width of crack X:length of crack	Y≤1/3L X≤5 Z 1/2T	<u>7</u> ≤ 1	1			•	film
		L:width of sidestep T:deepth of crack Z:thickness of single	Y≤1/3L X≤10 Z ≤1/2T		0				
		glass	Y≤1/3L X≤15 ≤1/2T	Z	0				
Crack			Cracks in any area		cted		•		Visual
Polarizer			≤0.8	Acc	cepted			•	Visual/

					contrast
	be applicable for up/bottom polarizer	0.8 <l≤1.0< td=""><td>Rejected</td><td>]  </td><td>by</td></l≤1.0<>	Rejected	]	by
	up/bottom polarizer	1.0 <l≤1.5< td=""><td>Rejected</td><td></td><td>Inspection standard</td></l≤1.5<>	Rejected		Inspection standard
		1.5 <l≤2.0< td=""><td>Rejected</td><td>_  </td><td>film</td></l≤2.0<>	Rejected	_	film
		Any seeable pola excursion in activ	arizer slanting or ve area will be rejected.		
			ge should be even and ntion within 1/3 of ill be rejected.		
		incorrect sticking	missing or extra, for polarizer and dirty on polarizer will be		
		seeable black sil	kscreen line from the cepted.		
		Refer to the drav	ving size requirement.		
End seal		UV glue of seal on the glass surface	Rejected		Visual/ contrast by
	L:The distance from the block to edge of glass.	The UV glue of seal overflow into the active area.	Rejected	•	Inspection standard film
		Direction of end seal is different from the drawing.	Rejected		
		Glue capacity of end seal < (1/3)*L	Rejected		
		the height and length of end seal is out of the drawing requirements.	Rejected		
Silkscreen line		silkscreen line overflow into the active area.	Rejected		Visual/ contrast by Inspection
		silkscreen line deviated in active area.	Rejected	•	standard
		bubble of silkscreen line ≥ 1/3 witdth of silkscreen line	Rejected		

PIN		Glue on PIN: the without pin clip wi solidification: PIN completely. The s touching will be re PIN deflection: if 5°, rejected; cot the drawing recontinuous glue of PIN glue stains or polarizer and glass PIN glue exceeds rejected. Missing or extra, IPIN loosen: no por drop. PIN:pin center exercipected. glue, rejected. glue, rejected. range: UV glue months of the properties of the pin distance rejected. Pin ust be same wit requirements.	•		Visual/ contrast by Inspection standard film	
Protective film		LCD protective filipolarizer and the raised ≤1/3 lengt from same directilength should be can be accepted.		•	Visual	
Rainbow		rainbow is not in active area.	Accepted			Visual/co ntrast by
		Rainbow in active area.	Rejected		•	golden sample
		with obvious discoloration and uneven color.	Rejected			
backgroud color		There are obvious different background color from the same product lot.	Rejected		•	Visual/co ntrast by golden sample

## NOTE:

Inspection condition:

Viewing distance for cosmetic inspection is 30cm with bare eyes, and under an environment of 800 lux(20W\*2---40W) light intensity, all directions for inspecting the sample should be within 45° against perpendicular line.

#### 14.0 PRECAUTION FOR USING LCM

- 1. When design the product with this LCD Module, make sure the viewing angle matches to its purpose of usage.
- 2. As LCD panel is made of glass substrate, Dropping the LCD module or banging it against hard objects may cause cracking or fragmentation. Especially at corners and edges.
- 3. Although the polarizer of this LCD Module has the anti-glare coating, always be careful not to scratch its surface. Use of a plastic cover is recommended to protect the surface of polarizer.
- 4. If the LCD module is stored at below specified temperature, the LC material may freeze and be deteriorated. If it is stored at above specified temperature, the molecular orientation of the LC material may change to Liquid state and it may not revert to its original state. Excessive temperature and humidity could cause polarizer peel off or bubble. Therefore, the LCD module should always be stored within specified temperature range.
- 5. Saliva or water droplets must be wiped off immediately as those may leave stains or cause color changes if remained for a long time. Water vapor will cause corrosion of ITO electrodes.
- 6. If the surface of LCD panel needs to be cleaned, wipe it swiftly with cotton or other soft cloth. If it is not still clean enough, blow a breath on the surface and wipe again.
- 7. The module should be driven according to the specified ratings to avoid malfunction and permanent damage. Applying DC voltage cause a rapid deterioration of LC material. Make sure to apply alternating waveform by continuous application of the M signal. Especially the power ON/OFF sequence should be kept to avoid latch-up of driver LSIs and DC charge up to LCD panel.
- 8. Mechanical Considerations
  - a) LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.
  - b) Do not tamper in any way with the tabs on the metal frame.
  - Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattern.
  - d) Do not touch the elastomer connector; especially insert a backlight panel (for example, EL).
  - e) When mounting a LCM makes sure that the PCB is not under any stress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.
  - f) Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing pixels.
- 9. Static Electricity
  - a) Operator

Ware the electrostatics shielded clothes because human body may be statically charged if not ware shielded clothes. Never touch any of the conductive parts such as the LSI pads; the copper leads on the PCB and the interface terminals with any parts of the human body.

b) Equipment

There is a possibility that the static electricity is charged to the equipment, which has a function of peeling or friction action (ex: conveyer, soldering iron, working table). Earth the equipment through proper resistance (electrostatic earth: 1x10<sup>8</sup> ohm).

Only properly grounded soldering irons should be used.

If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

c) Floor

Floor is the important part to drain static electricity, which is generated by operators or equipment.

There is a possibility that charged static electricity is not properly drained in case of insulating floor. Set the electrostatic earth (electrostatic earth:  $1x10^8$  ohm).

d) Humidity

Proper humidity helps in reducing the chance of generating electrostatic charges. Humidity should be kept over 50%RH.

e) Transportation/storage

The storage materials also need to be anti-static treated because there is a possibility that the human body or storage materials such as containers may be statically charged by friction or peeling.

The modules should be kept in antistatic bags or other containers resistant to static for storage.

f) Soldering

Solder only to the I/O terminals. Use only soldering irons with proper grounding and no leakage.

Soldering temperature: 340~370° C

Soldering time: 3 to 4 sec.

Use eutectic solder with resin flux fill.

If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed afterwards.

g) Others

The laminator (protective film) is attached on the surface of LCD panel to prevent it from scratches or stains. It should be peeled off slowly using static eliminator.

Static eliminator should also be installed to the workbench to prevent LCD module from static charge.

- 10. Operation
  - Driving voltage should be kept within specified range; excess voltage shortens display life.
  - b) Response time increases with decrease in temperature.
  - c) Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".
  - d) Mechanical disturbance during operation (such as pressing on the viewing area) may cause the segments to appear "fractured".
- 11. If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. The toxicity is extremely low but caution should be exercised at all the time.
- 12. Disassembling the LCD module can cause permanent damage and it should be strictly avoided.
- 13. LCD retains the display pattern when it is applied for long time (Image retention). To prevent image retention, do not apply the fixed pattern for a long time. Image retention is not a deterioration of LCD. It will be removed after display pattern is changed.
- 14. Do not use any materials, which emit gas from epoxy resin (hardener for amine) and silicone adhesive agent (dealcohol or deoxym) to prevent discoloration of polarizer due to gas.
- 15. Avoid the exposure of the module to the direct sunlight or strong ultraviolet light for a long time.